



## Applications

- OFN applications for mobile phones, remote controls and portable electronic equipment
- Ultra-low power wireless laser mouse: 27 MHz, 2.4 GHz and Bluetooth
- Suitable for laser USB mouse applications

## Technical specifications

**Table 1. Technical specifications**

Resolution	Programmable up to 3200 cpi
Pixel size	30.4 $\mu\text{m}$
Array size	20 x 20 pixels
Frame rate	up to 4000 fps
Tracking performance	<b>Laser or LED:</b> 1m/s Very low drift
Supply voltage	1V to 1.6V <sup>(1)</sup> , 1.8V direct drive or 2.2V to 3.0V
Operating temperature	-20°C to 60°C

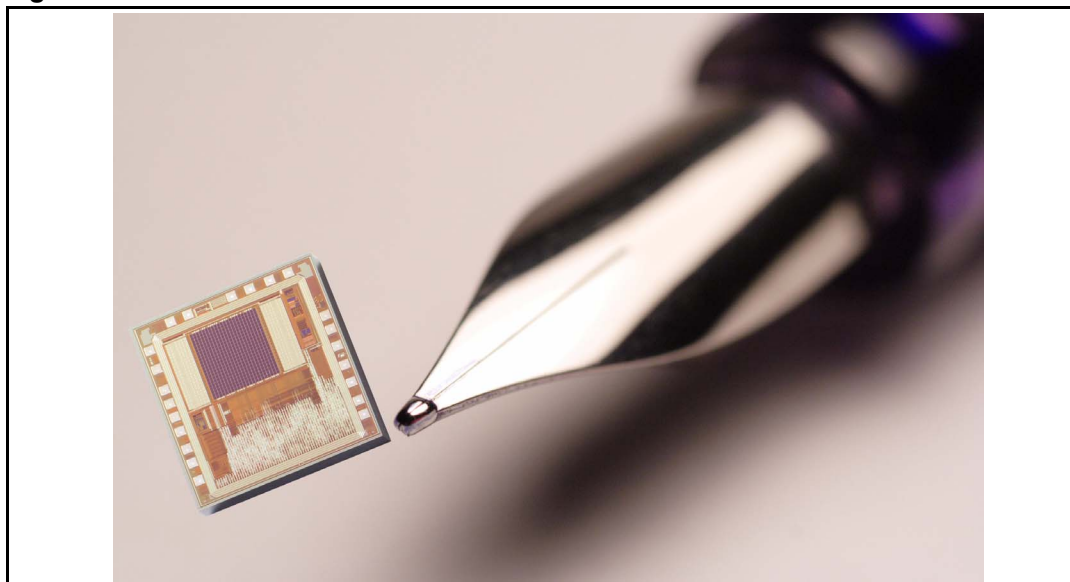
1. Using internal boost converter controller.

## Silicon specifications

**Table 2. Silicon specifications**

Wafer thickness	775 $\mu\text{m}$ , 375 $\mu\text{m}$ or 180 $\mu\text{m}$ (all +/- 20 $\mu\text{m}$ )
Bond pad size	81 x 81 $\mu\text{m}$
Minimum bond pitch	140 $\mu\text{m}$

**Figure 1. VD5376 die**



## Ordering information

**Table 3. Ordering information**

Order code	Description
VD5376/UW	Unsawn wafer - 775 µm
VD5376CA/SW	Sawn Wafer - 375 µm
VD5376CB/UW	Unsawn wafer - 180 µm
STV-376-E04	Generic testboard

## Revision history

Date	Revision	Changes
2-Mar-2010	1	Initial release.
14-Jun-2010	2	Amendments made to data in <a href="#">Table 1: Technical specifications</a> , <a href="#">Table 2: Silicon specifications</a> to correct errors. New order codes added to <a href="#">Table 3: Ordering information</a> .

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